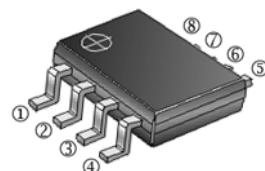


RoHS Compliant Product  
A suffix of "-C" specifies halogen & lead-free

## DESCRIPTION

These N-Channel enhancement mode power field effect transistors are using trench DMOS technology. This advanced technology has been especially tailored to minimize on-state resistance, provide superior switching performance, and withstand high energy pulse in the avalanche and commutation mode. These devices are well suited for high efficiency fast switching applications.

**SOP-8**



## FEATURES

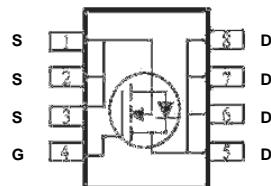
- Fast switching
- Green Device Available

## APPLICATIONS

- MB / VGA / Vcore
- POL Applications
- SMPS 2<sup>nd</sup> SR

## PACKAGE INFORMATION

| Package | MPQ | Leader Size |
|---------|-----|-------------|
| SOP-8   | 3K  | 13 inch     |



## ORDER INFORMATION

| Part Number | Type                            |
|-------------|---------------------------------|
| SSG15N03-C  | Lead (Pb)-free and Halogen-free |

## ABSOLUTE MAXIMUM RATINGS ( $T_c=25^\circ\text{C}$ unless otherwise specified)

| Parameter                                      | Symbol          | Ratings  | Unit |
|--|-----------------|----------|------|
| Drain-Source Voltage                           | $V_{DS}$        | 30       | V    |
| Gate-Source Voltage                            | $V_{GS}$        | $\pm 20$ | V    |
| Continuous Drain Current                       | $I_D$           | 15       | A    |
|  |                 | 9.5      |      |
| Pulsed Drain Current <sup>1</sup>              | $I_{DM}$        | 60       | A    |
| Total Power Dissipation                        | $P_D$           | 4        | W    |
| Operating Junction & Storage Temperature Range | $T_J, T_{STG}$  | -55~150  | °C   |
| Thermal Resistance Ratings                     |                 |          |      |
| Thermal Resistance Junction-Ambient            | $R_{\theta JA}$ | 85       | °C/W |
| Thermal Resistance Junction-Case               | $R_{\theta JC}$ | 31       |      |

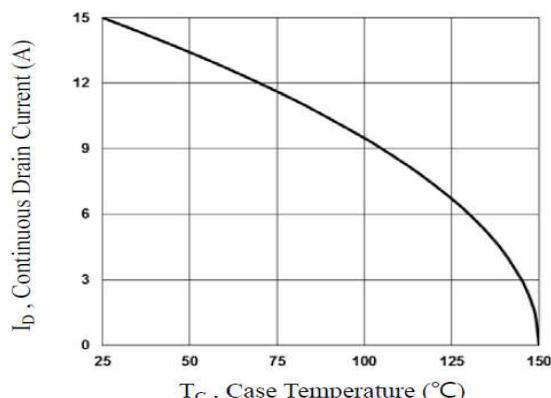
**ELECTRICAL CHARACTERISTICS** ( $T_J=25^\circ\text{C}$  unless otherwise specified)

| Parameter                          | Symbol              | Min. | Typ. | Max.      | Unit                                   | Test conditions   |
|------------------------------------|---------------------|------|------|-----------|--|---|
| Drain-Source Breakdown Voltage     | $V_{(BR)DSS}$       | 30   | -    | -         | V                                      | $V_{GS}=0\text{V}$ , $I_D=250\mu\text{A}$   |
| Gate Threshold Voltage             | $V_{GS(\text{th})}$ | 1.2  | -    | 2.5       | V                                      | $V_{DS}=V_{GS}$ , $I_D=250\mu\text{A}$  |
| Gate-Source Leakage Current        | $I_{GSS}$           | -    | -    | $\pm 100$ | nA                                     | $V_{GS} = \pm 20\text{V}$ , $V_{DS}=0\text{V}$                                    |
| Drain-Source Leakage Current       | $I_{DSS}$           | -    | -    | 1         | $\mu\text{A}$                          | $V_{DS}=24\text{V}$ , $V_{GS}=0\text{V}$  |
|                                    |                     | -    | -    | 10        |  |   |
|                                    |                     | -    | -    | 8.5       | mΩ                                     |   |
| Static Drain-Source On-Resistance  |                     | -    | -    | 11        | $V_{GS}=4.5\text{V}$ , $I_D=8\text{A}$ |   |
| Gate Resistance                    | $R_g$               | -    | 3.2  | -         | Ω                                      | $V_{DS}=V_{GS}=0\text{V}$ , $f=1\text{MHz}$                                       |
| Forward Transconductance           | $g_{fs}$            | -    | 22   | -         | S                                      | $V_{DS}=10\text{V}$ , $I_D=8\text{A}$   |
| Total Gate Charge                  | $Q_g$               | -    | 23.2 | -         | nC                                     | $V_{DS}=15\text{V}$<br>$V_{GS}=10\text{V}$<br>$I_D=1\text{A}$                     |
| Gate-Source Charge                 | $Q_{gs}$            | -    | 3.2  | -         |  |   |
| Gate-Drain Change                  | $Q_{gd}$            | -    | 3.7  | -         |  |   |
| Turn-on Delay Time                 | $T_{d(on)}$         | -    | 7    | -         | nS                                     | $V_{DD}=10\text{V}$<br>$V_{GS}=10\text{V}$<br>$I_D=30\text{A}$<br>$R_G=2.7\Omega$ |
| Rise Time                          | $T_r$               | -    | 76.6 | -         |  |   |
| Turn-off Delay Time                | $T_{d(off)}$        | -    | 27.1 | -         |  |   |
| Fall Time                          | $T_f$               | -    | 52.6 | -         |  |   |
| Input Capacitance                  | $C_{iss}$           | -    | 1180 | -         | pF                                     | $V_{DS}=15\text{V}$<br>$V_{GS}=0\text{V}$<br>$f=1\text{MHz}$                      |
| Output Capacitance                 | $C_{oss}$           | -    | 177  | -         |  |   |
| Reverse Transfer Capacitance       | $C_{rss}$           | -    | 132  | -         |  |   |
| <b>Source-Drain Diode</b>          |                     |      |      |           |  |   |
| Continuous Source Current          | $I_s$               | -    | -    | 15        | A                                      | $V_{GS}=V_{DS}=0\text{V}$ ,<br>Force Current                                      |
| Pulsed Source Current <sup>3</sup> | $I_{SM}$            | -    | -    | 30        |  |   |
| Forward on Voltage <sup>3</sup>    | $V_{SD}$            | -    | -    | 1         | V                                      | $I_s=1\text{A}$ , $V_{GS}=0\text{V}$  |

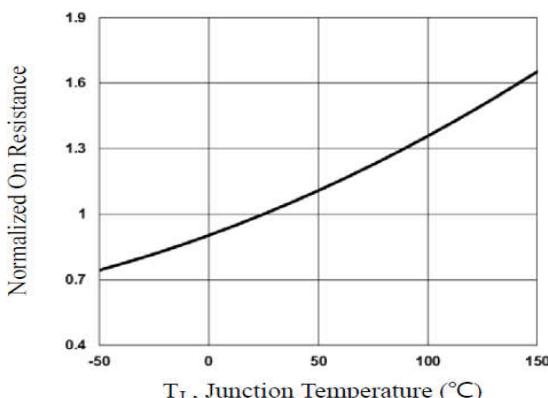
Notes:

1. Repetitive rating : pulsed width limited by maximum junction temperature
2. The data tested by pulsed , pulse width  $\leq 300\mu\text{s}$  , duty cycle  $\leq 2\%$ .
3. Essentially independent of operating temperature.

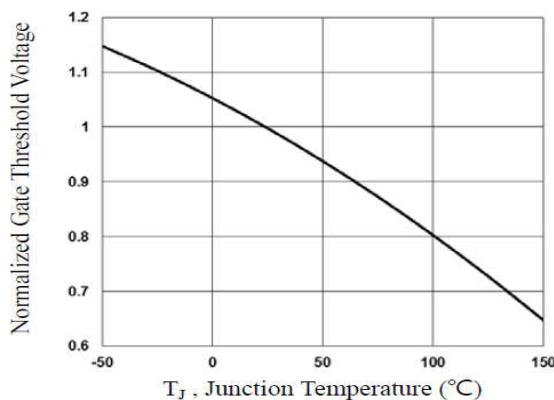
### TYPICAL CHARACTERISTICS CURVE



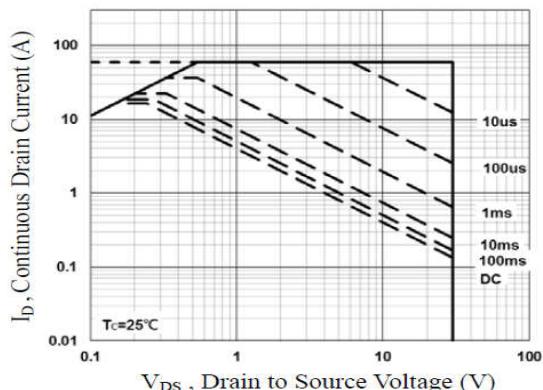
**Fig.1** Continuous Drain Current vs.  $T_c$



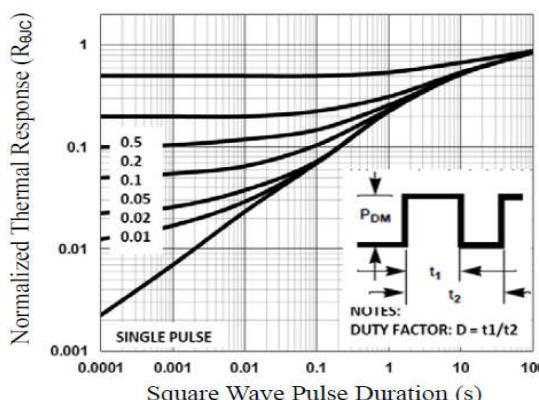
**Fig.2** Normalized  $R_{DSON}$  vs.  $T_j$



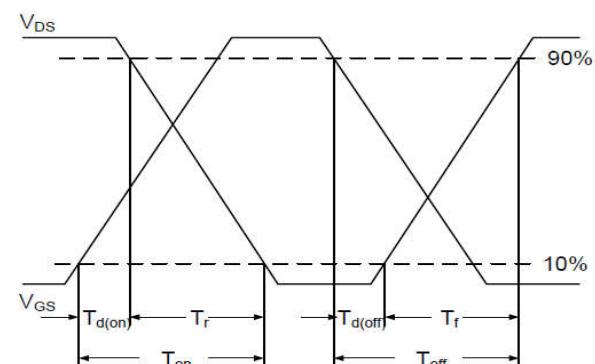
**Fig.3** Normalized  $V_{th}$  vs.  $T_j$



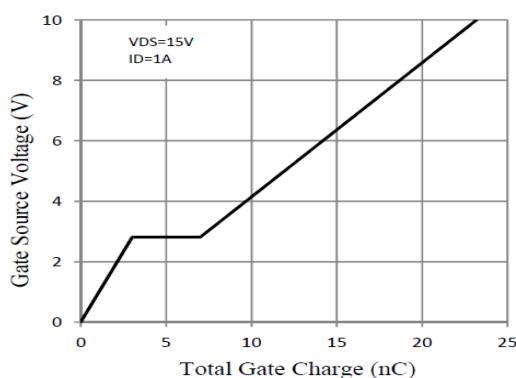
**Fig.4** Maximum Safe Operation Area



**Fig.5** Normalized Transient Impedance



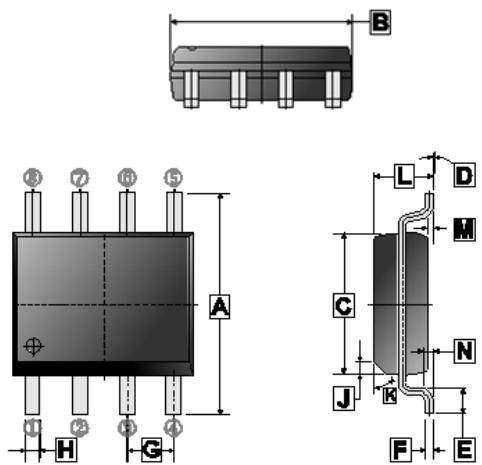
**Fig.6** Switching Time Waveform



**FIG. 7** Gate Charge Characteristics

## PACKAGE OUTLINE DIMENSIONS

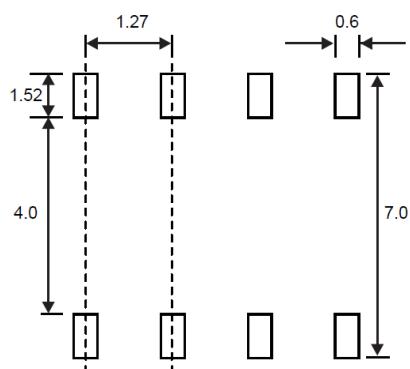
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| REF. | Millimeter |      |
|------|------------|------|
|      | Min.       | Max. |
| A    | 5.80       | 6.20 |
| B    | 4.38       | 5.20 |
| C    | 3.70       | 4.10 |
| D    | 0°         | 8°   |
| E    | 0.40       | 1.27 |
| F    | 0.10       | 0.26 |
| G    | 1.27 TYP.  |      |
| H    | 0.30       | 0.51 |
| J    | 0.375 REF. |      |
| K    | 45° REF.   |      |
| L    | 1.30       | 1.80 |
| M    | 0          | 0.25 |
| N    | 0.25 REF.  |      |

## MOUNTING PAD LAYOUT

SOP-8



\*Dimensions in millimeters